



Advanced Readout ASICs for Multi-Element CdZnTe Sensors

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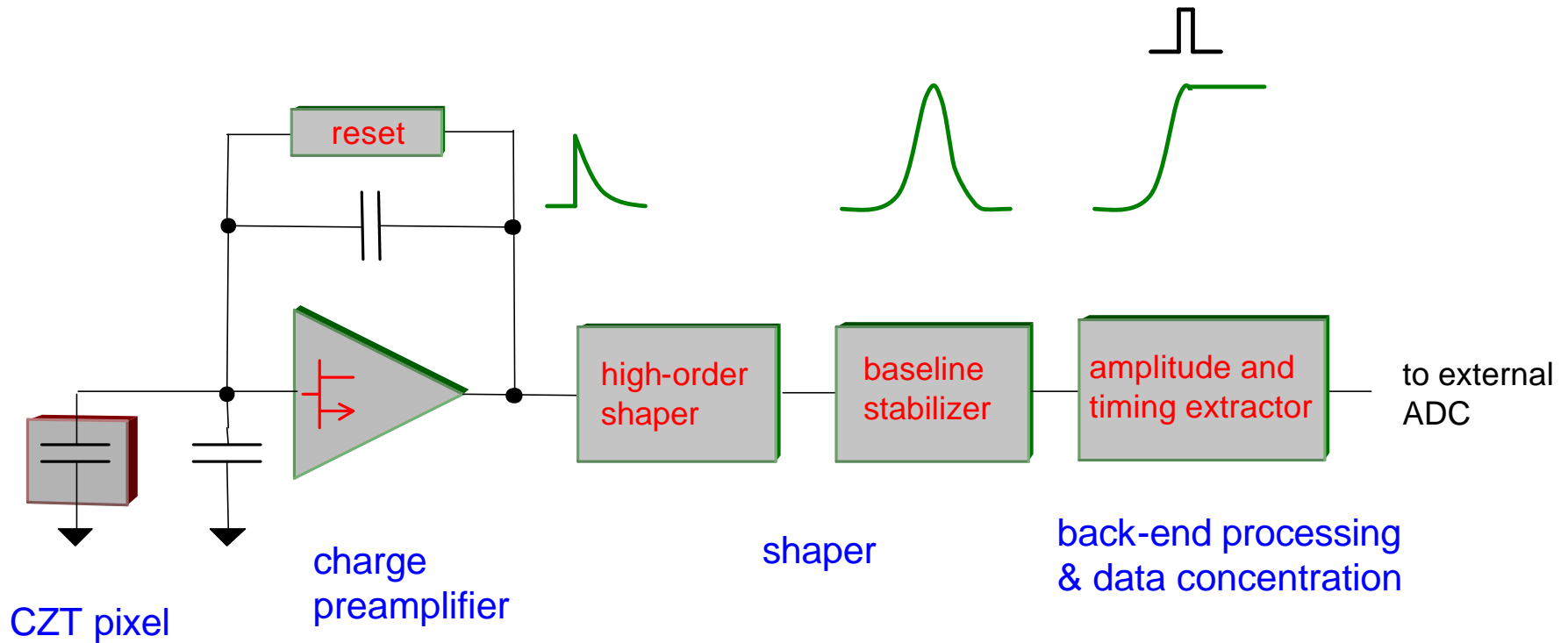
Outline

- Front-end ASICs
 - input MOSFET optimization
 - self-adaptive continuous reset of the preamplifier
 - high order shaping
 - output baseline stabilizer (BLH)
 - summary of the first generation
- Data-concentration ASICs
 - two-phase peak detector
 - derandomization process
 - the 32-channel prototype
 - high reliability
 - high stability
 - ease of use (plug & play)
 - spectroscopic quality
 - data concentration optimization

The BNL-eV cooperation

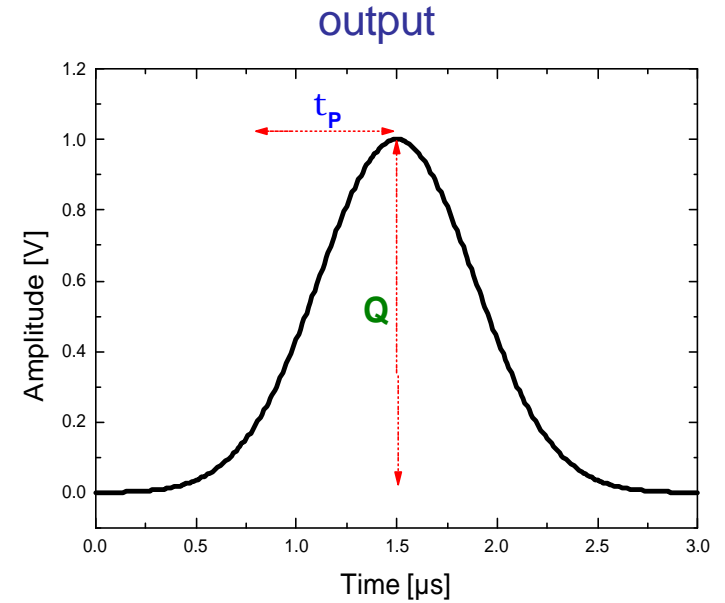
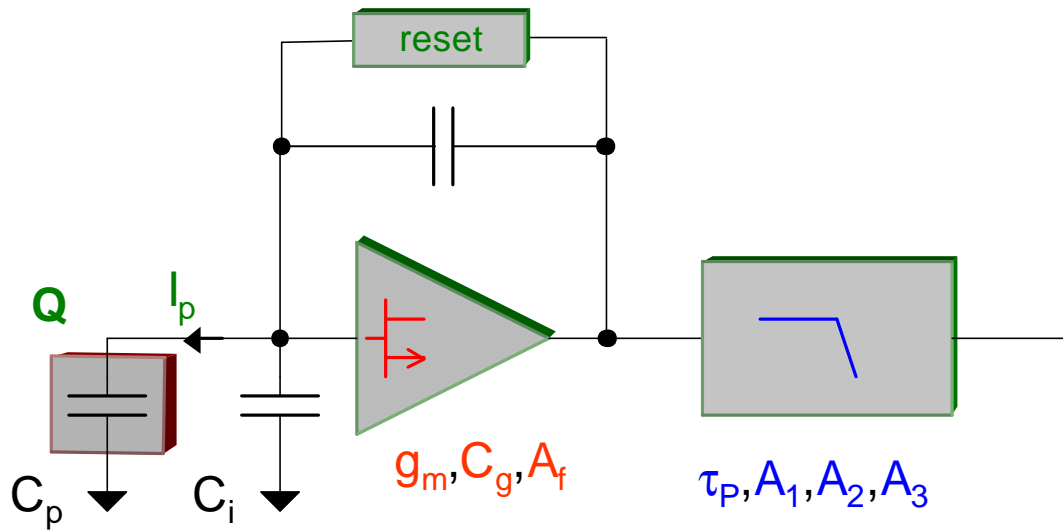
- Started in September **1997**
- First 4 channel front-end ASIC prototype available in April **1999**
- As of Jun **2002** :
 - four front-end ASICs completed (three in production)
 - number of channels (4 - 16)
 - gain (30 - 240 mV/fC, settable)
 - speed (unipolar/bipolar shaping, 0.2 - 4 μ s peaking time, settable)
 - input MOSFET (matching 3 or 12 pF input capacitance)
 - one 32-channels arbitration - multiplexing mixed-signal ASIC completed
 - one 32-channels arbitration - peak detection - derandomizing - multiplexing mixed-signal ASIC prototype under development (in fabrication)

Preamplification and processing of signals from CZT



- high reliability
- ease of use
- spectroscopic quality
- data concentration optimization

Input MOSFET optimization

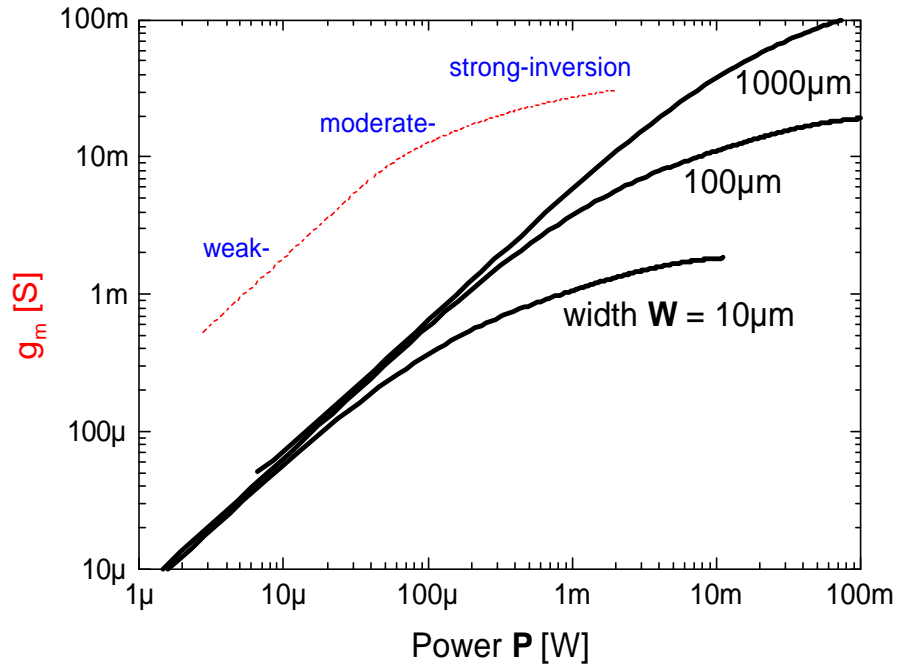


$$\text{ENC}^2 = A_1 \tau_p \frac{(C_p + C_i + C_g)^2}{g_m} + A_2 A_f (C_p + C_i + C_g)^2 + \frac{A_3}{\tau_p} (I_p + I_{rst})$$

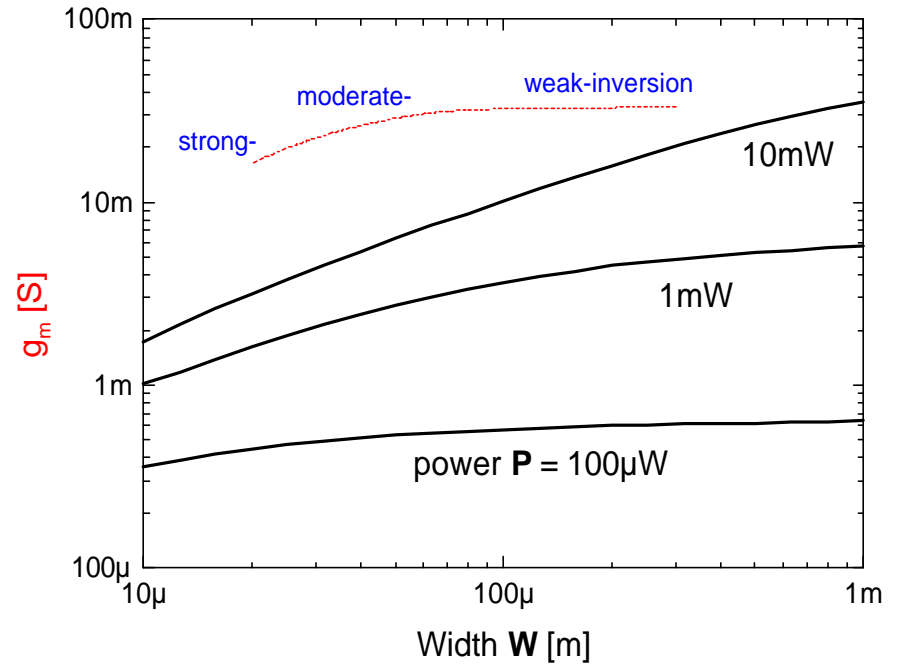
g_m, C_g, A_f , are functions of input MOSFET width \mathbf{W} and power \mathbf{P}

Input MOSFET optimization

g_m vs P



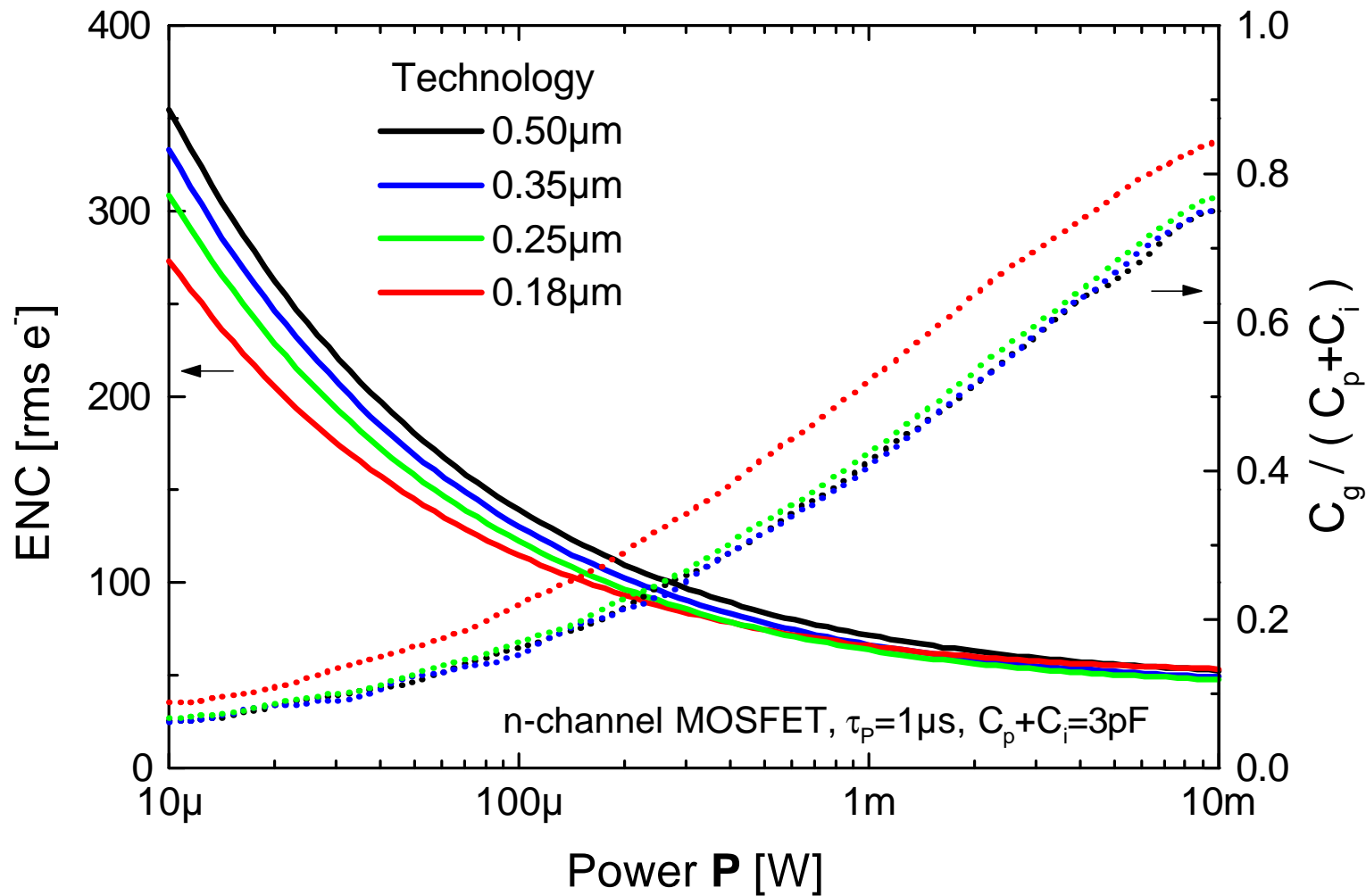
g_m vs W



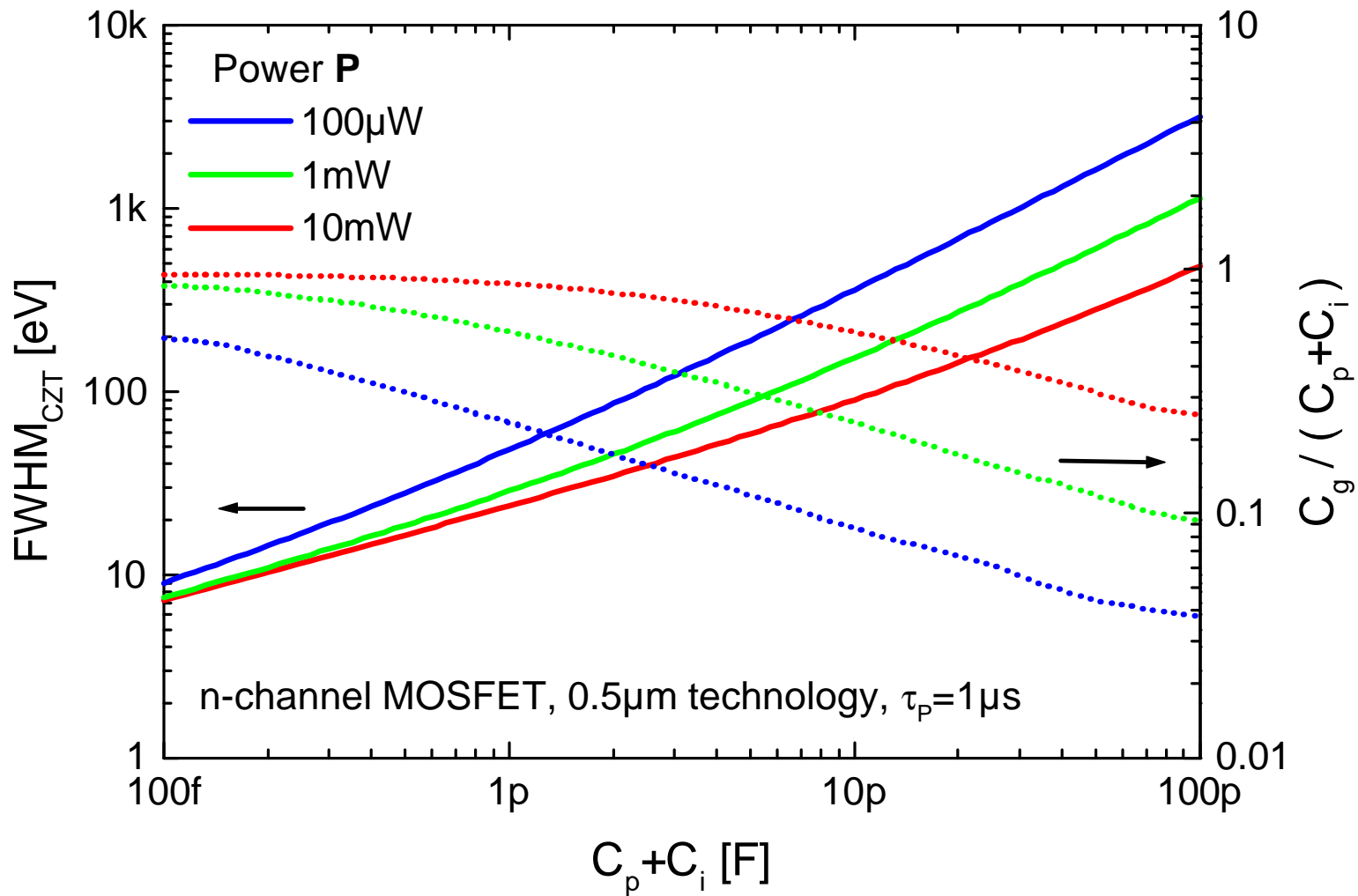
$$C_g \approx (C_{ox}L + C_{ov}) \cdot W$$

$$A_f \approx K_f / (C_{ox}L \cdot W)$$

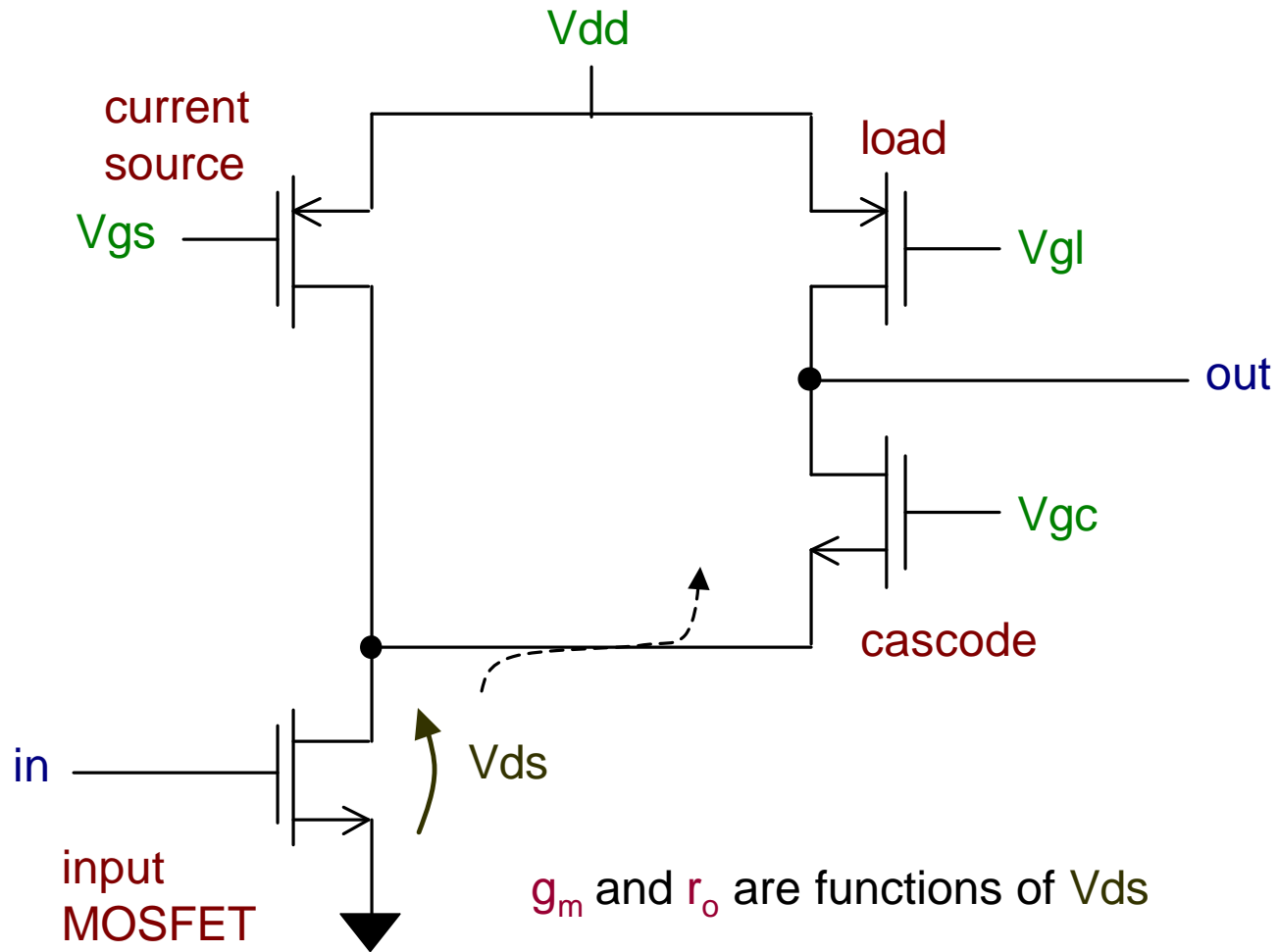
Input MOSFET optimization



Input MOSFET optimization

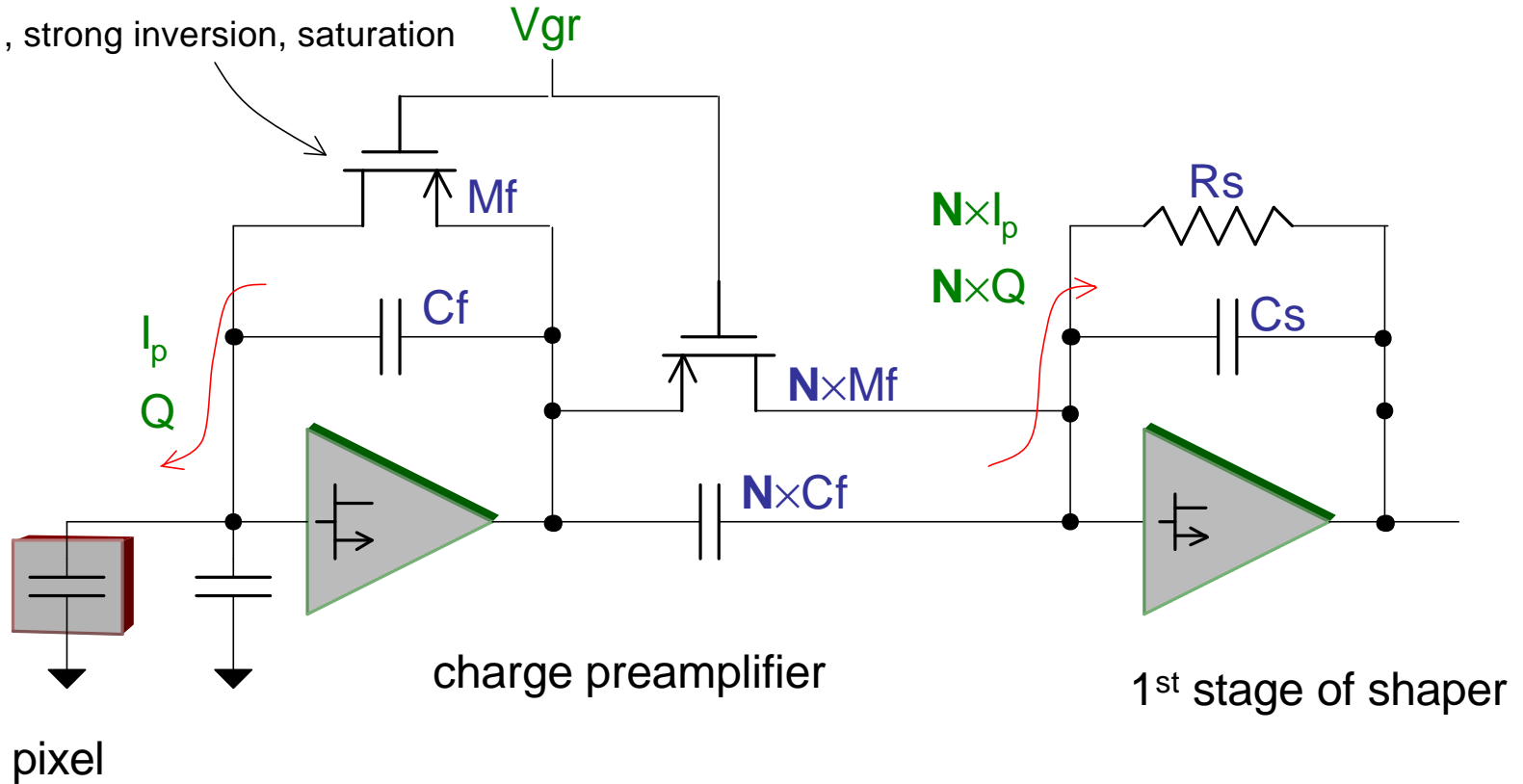


Input MOSFET optimization



Continuous reset of the preamplifier

$L/W \gg 1$, strong inversion, saturation

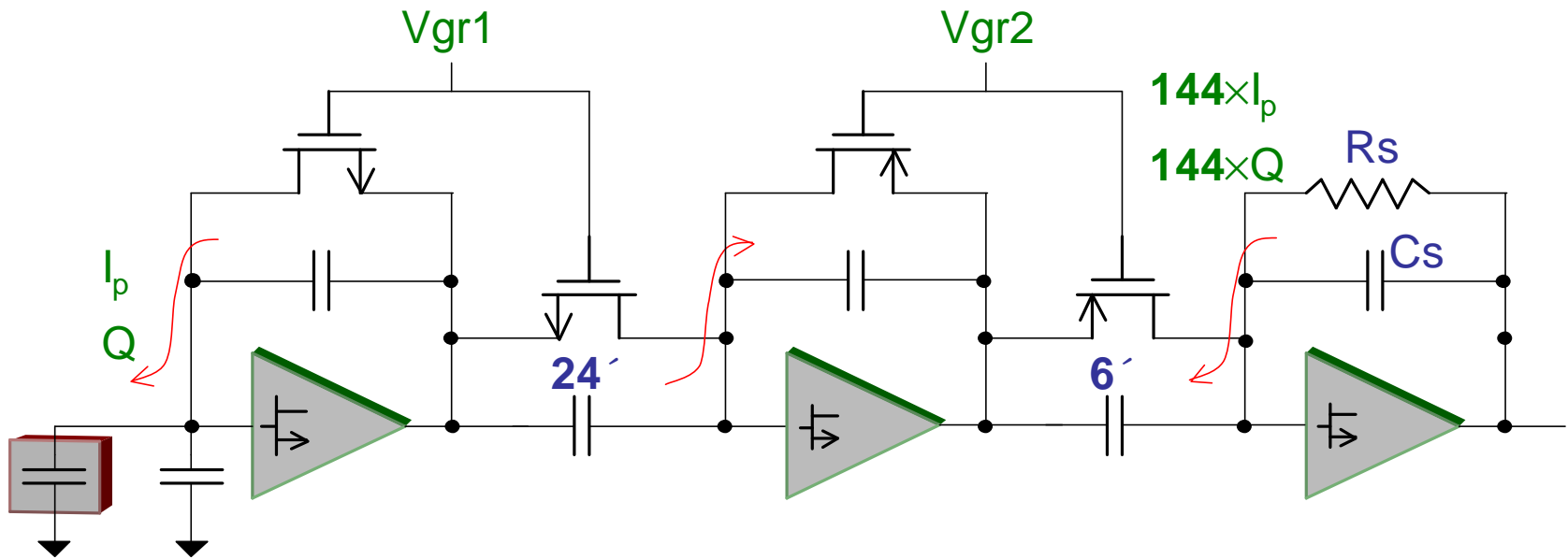


- current gain equal to N
- fully linear
- **self-adapts** to leakage current
- minimum noise contribution

Continuous reset of the preamplifier

$$\frac{2kT}{R_s} \frac{1}{N^2} \equiv q \cdot I_{eq}$$

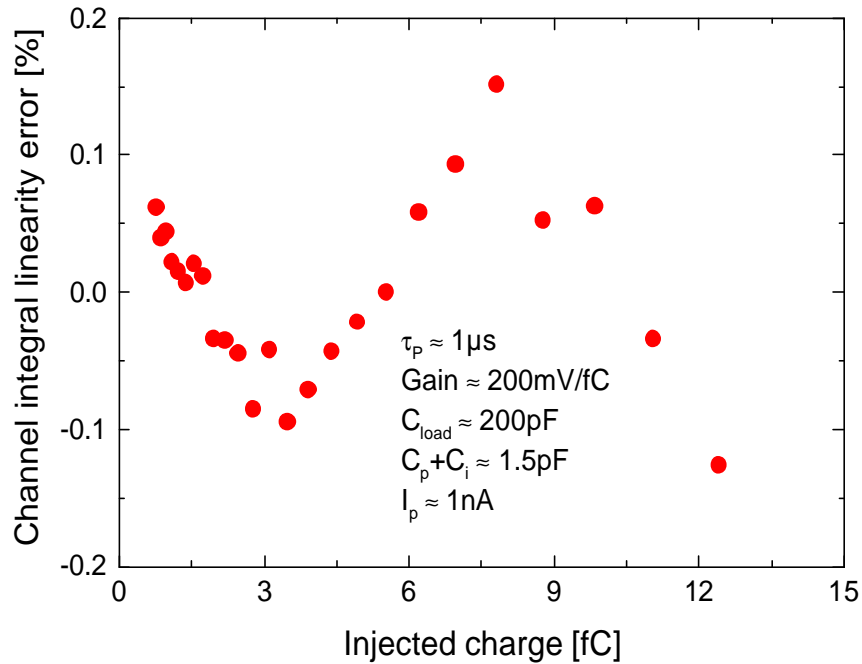
$$R_s \approx 100k\Omega \rightarrow I_{eq} \approx 1nA$$



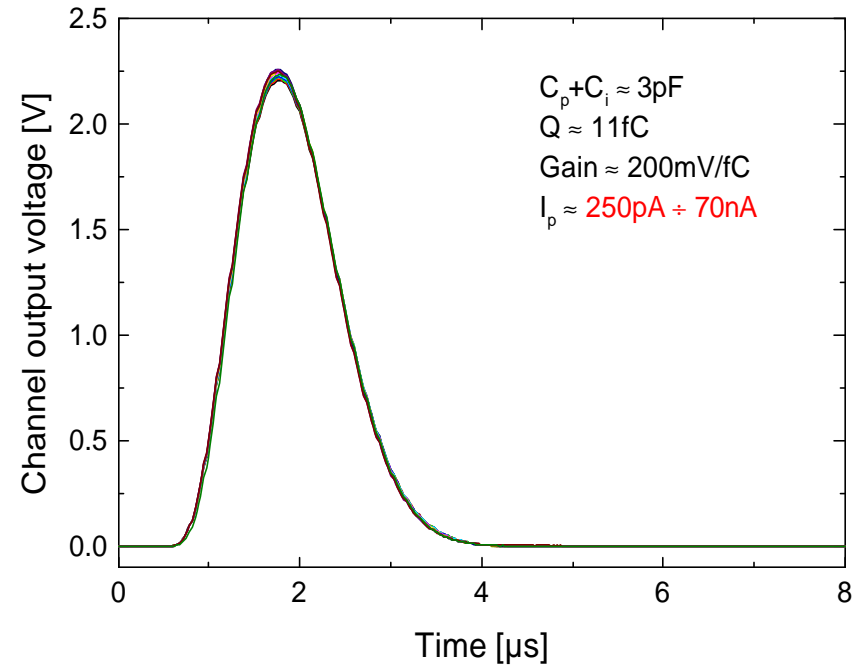
$$R_s \approx 100k\Omega \rightarrow I_{eq} \approx 25pA$$

Continuous reset of the preamplifier

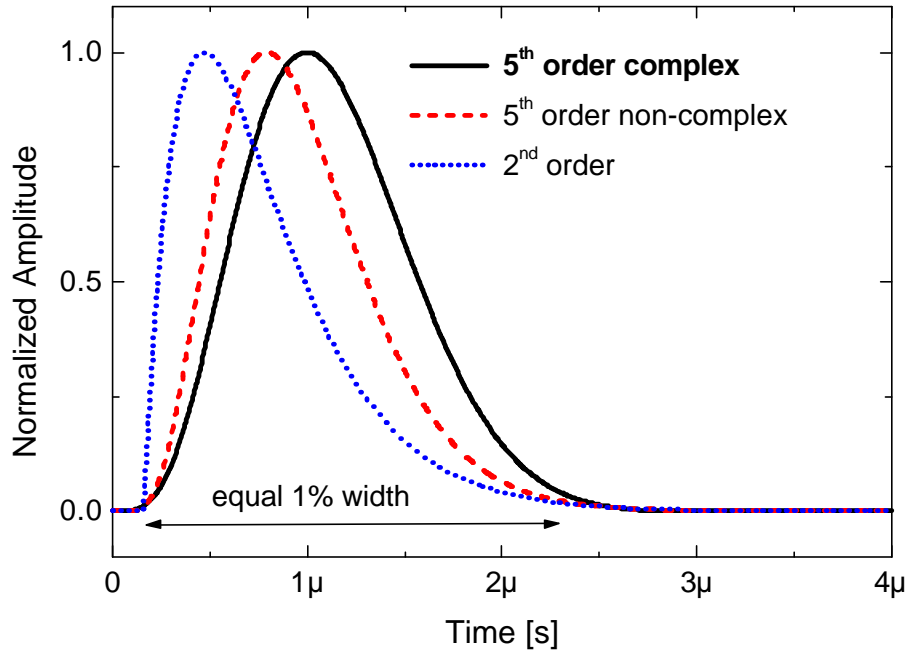
linearity



output vs pixel leakage current



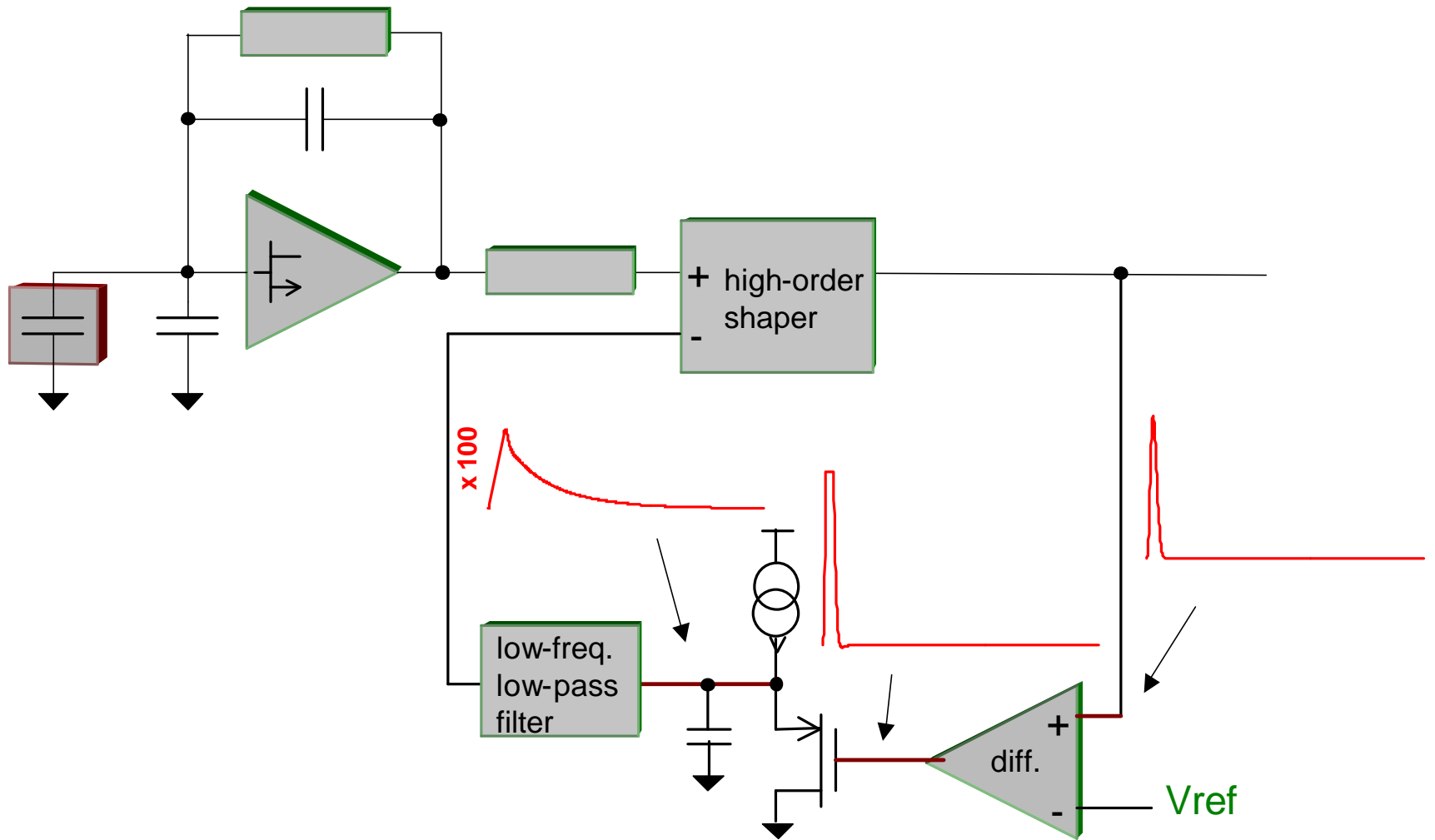
High order shaping



	a
5th cpx	1
5 th	1.24
2 nd	2.64

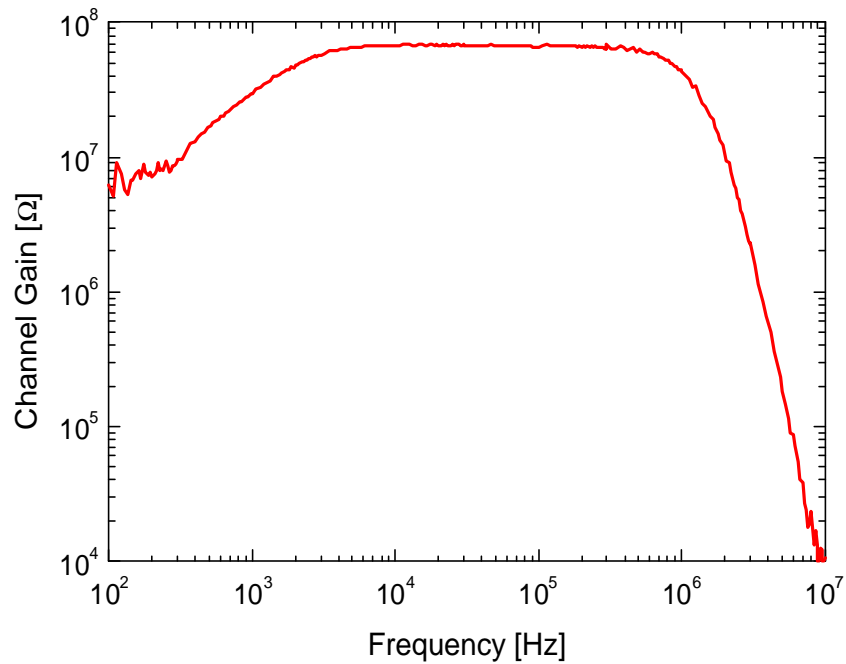
$$ENC^2 = a A_{wtw} \frac{(C_p + C_i + C_g)^2}{g_m} + \dots$$

Output baseline stabilizer

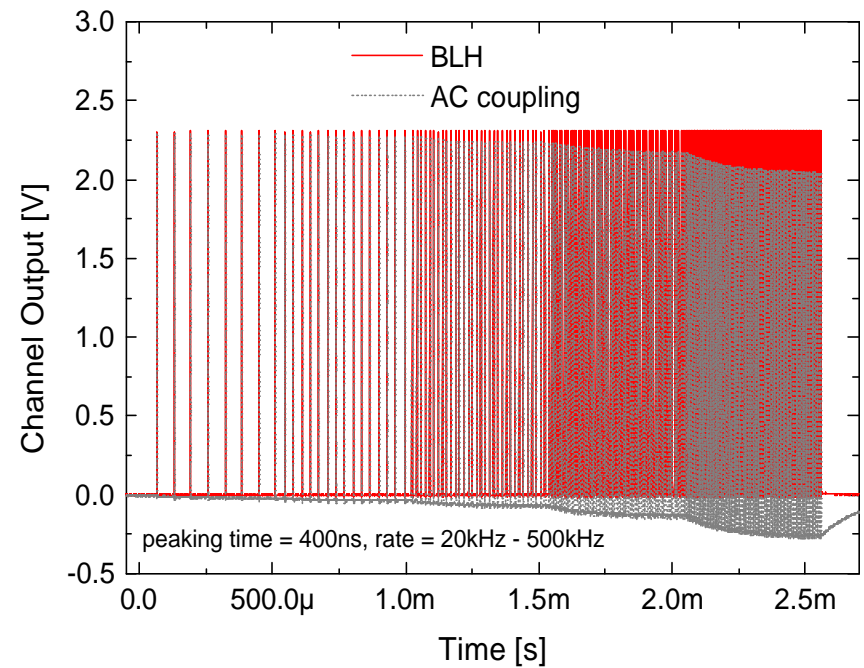


Output baseline stabilizer

transfer function



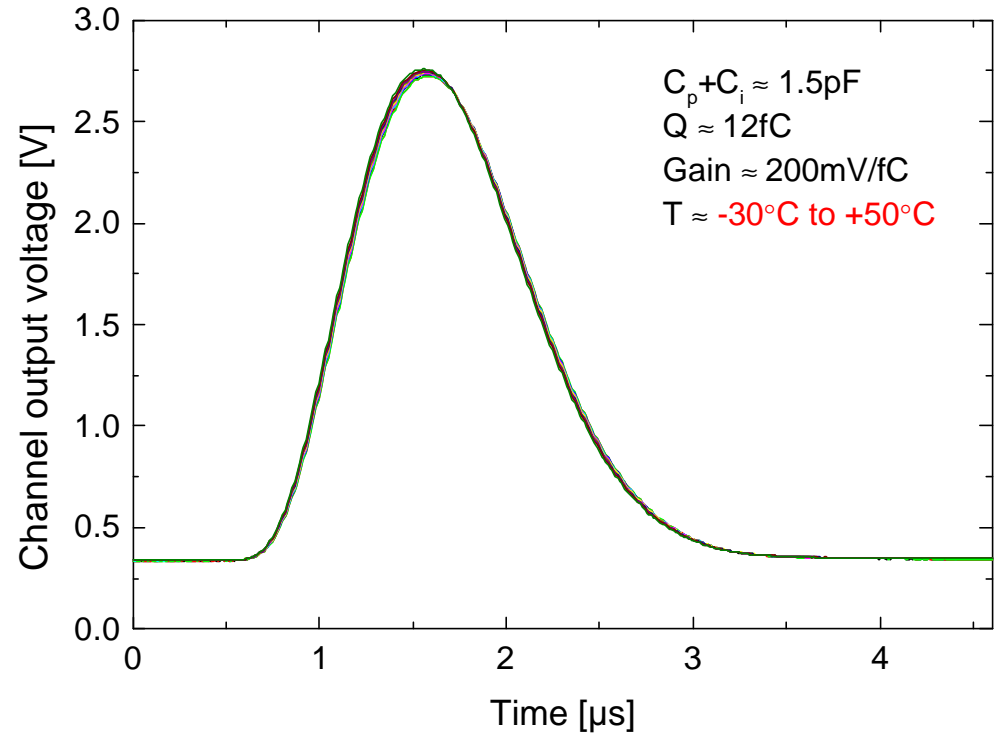
performance at high rate



First generation of front-end ASICs

other features

- plug & play
- per-channel test capacitor
- programmable gain
- programmable peaking time
- high output drive capability
- high stability vs temperature →





The first generation of front-end ASICs

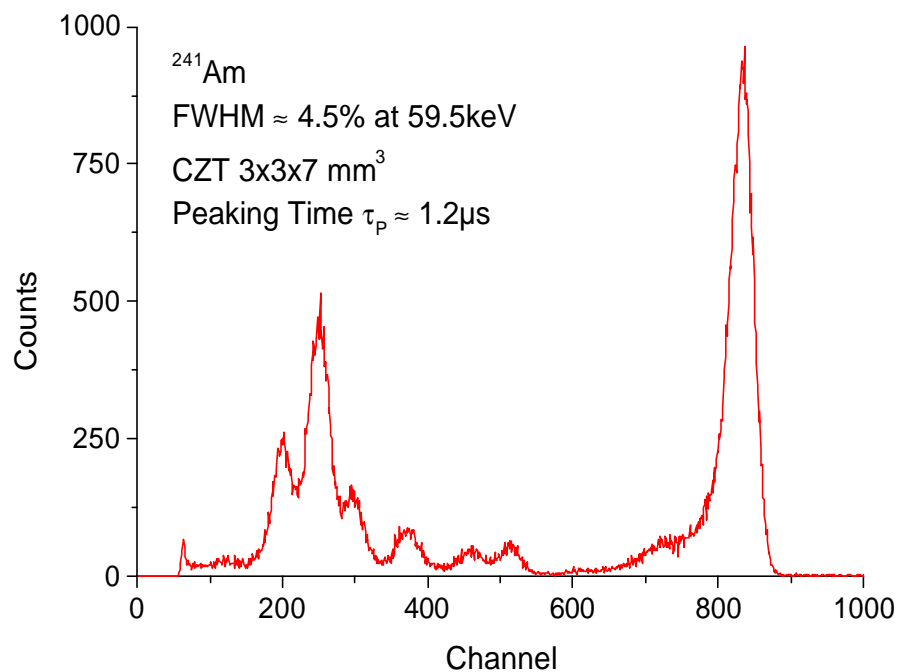


ASIC	Pixel capacitance [pF]	Channel count	Peaking time [μ s]	Gain [mV/fC]	Power / channel [mW]	ENC [rms. e ⁻]	Applications
General purpose	3	16	0.6, 1.2, 2.0, 4.0	30, 50, 100, 200	18	30+20/pF	<i>LFOV Gamma Camera SFOV Gamma Camera Nuclear Safeguards</i>
Medium speed	3	4	0.4	200	18	29+27/pF	<i>Down Hole Well Logging X-Ray Diffraction Gauges</i>
High speed bipolar	3	8	0.2	240	18	42+44/pF	<i>Bone Densitometry Pulse Mode CT Industrial X-Ray</i>
High capacitance	12	8	0.6, 1.2, 2.0, 4.0	30, 50, 100, 200	35	57+10/pF	<i>Industrial Strip Detectors Backscatter Gauges Large Area Detector</i>

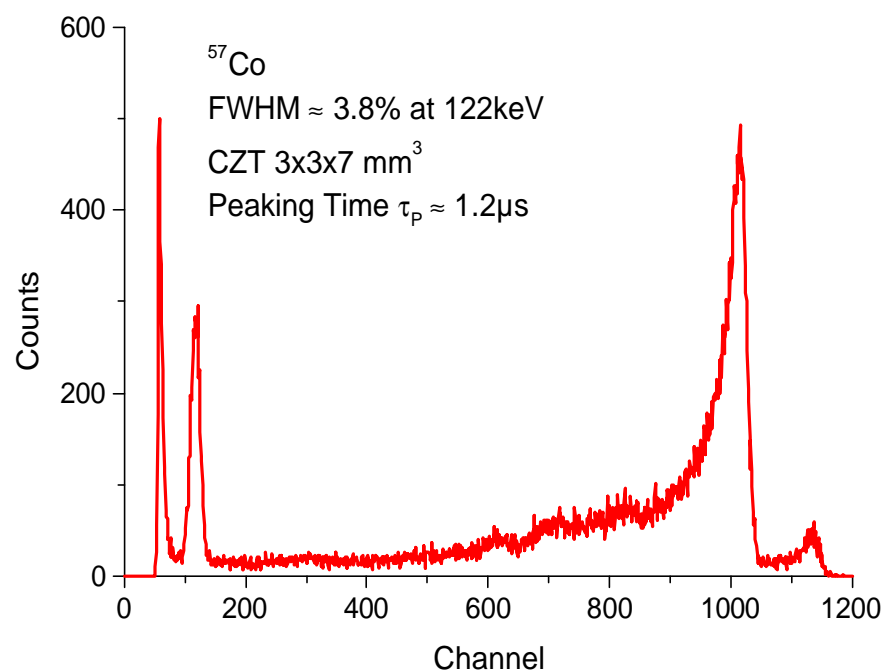
Technology : 0.5 μ m CMOS SP3M

CZT – ASIC spectra measurements

^{241}Am spectrum

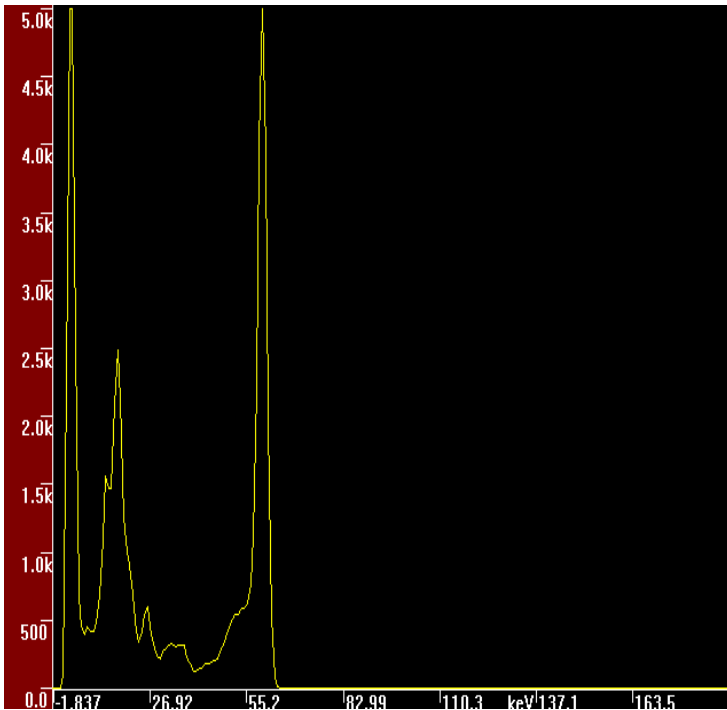


^{57}Co spectrum



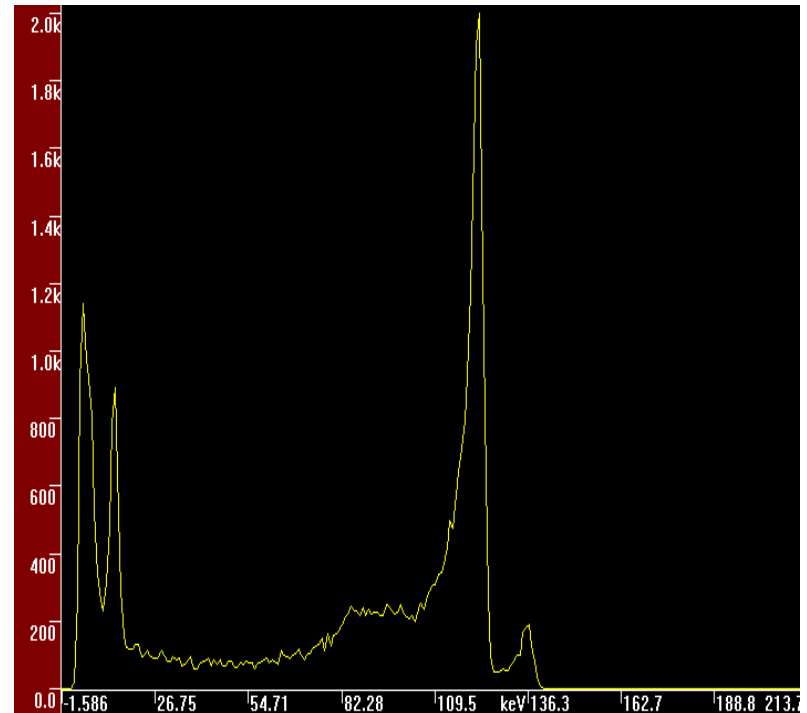
CZT – ASIC spectra measurements

^{241}Am spectrum



- detector thickness 3mm
- detector bias -600V
- resolution 4.3% at 59keV
- gain 200mV/fC
- peaking time 1.2 μs

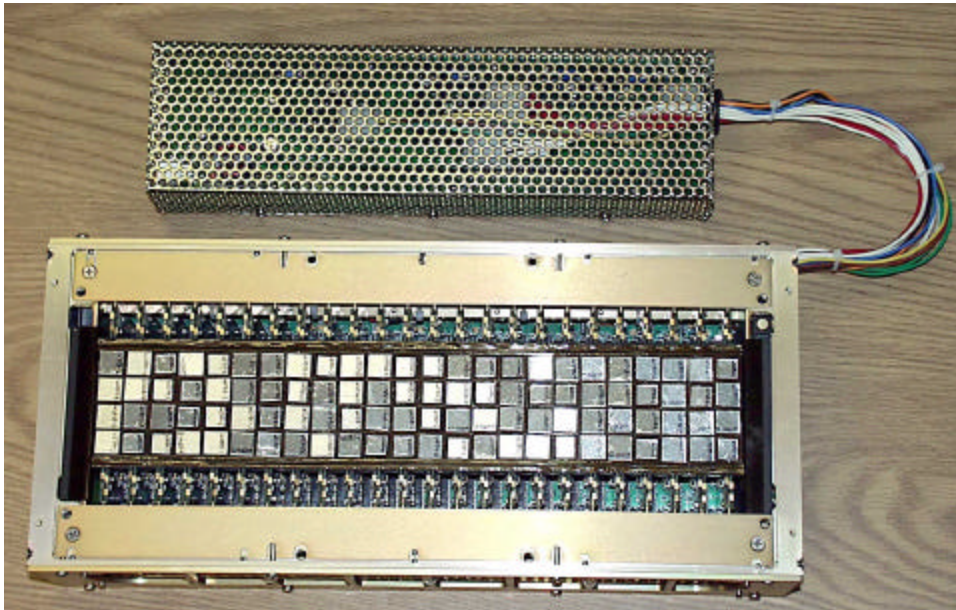
^{57}Co spectrum



- detector thickness 3mm
- detector bias -600V
- resolution 3.5% at 122keV, 21.8% at 14keV
- gain 200mV/fC
- peaking time 1.2 μs

CZT – ASIC applications

Solstice Gamma camera



- 96 CZT crystals
- 3072 pixels
- 196 front-end ASICs
- 1.3M events/second
- average FWHM 3.8% at 122keV

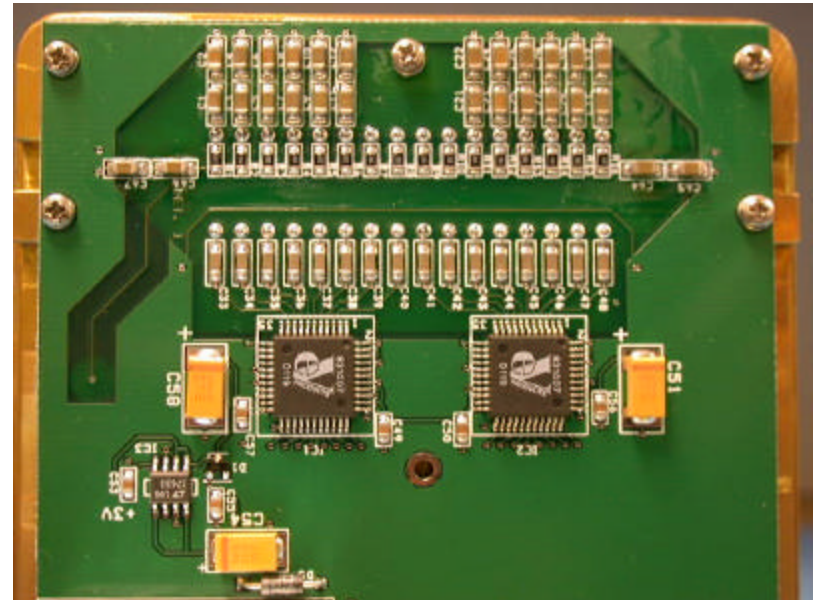
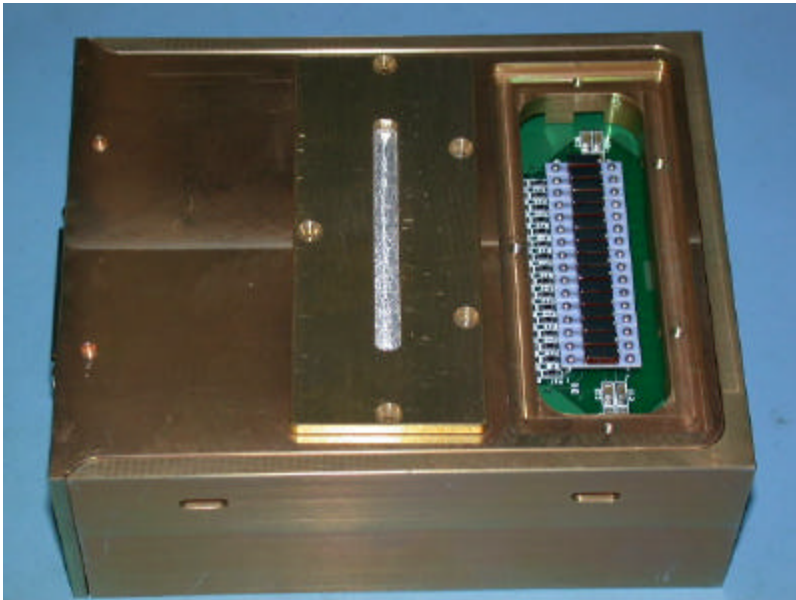
eZ-SCOPE hand held Gamma camera



- 1 CZT crystal
- 256 pixels
- 16 front-end ASICs
- 4.8M events/second
- average FWHM 4.0% at 122keV

CZT – ASIC applications

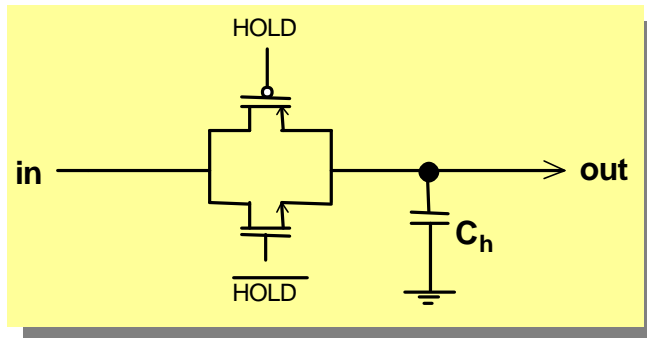
Bone Densitometry – GE Lunar Detector



- 16 CZT crystals
- 16 pixels 3 x 7 x 3 mm³
- 2 front-end ASICs
- DEXA (Dual Energy X-ray Absorptiometry)
- ASICs replaced 17 circuit boards (over 500 components) and improved performances

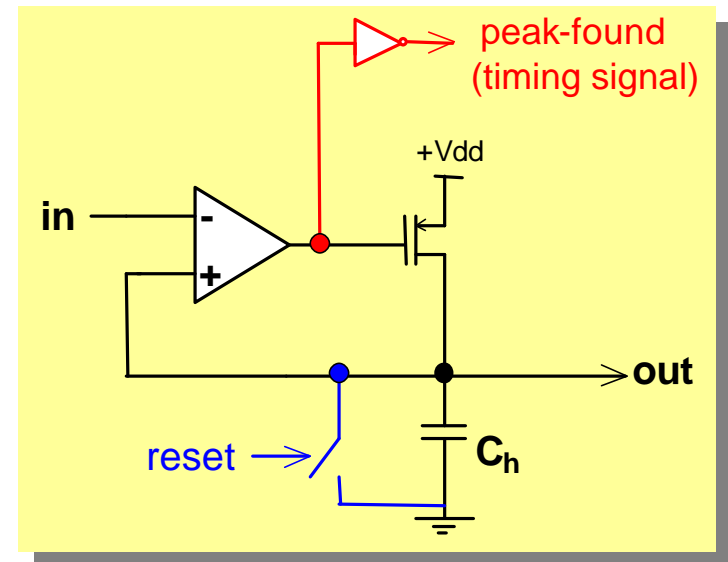
Pulse amplitude extraction : classical CMOS configurations

sample/hold



- **timing signal needed**
 - switch charge injection
 - poor drive capability
 - deadtime until readout
-
- + power dissipation

peak detect/hold (PDH)

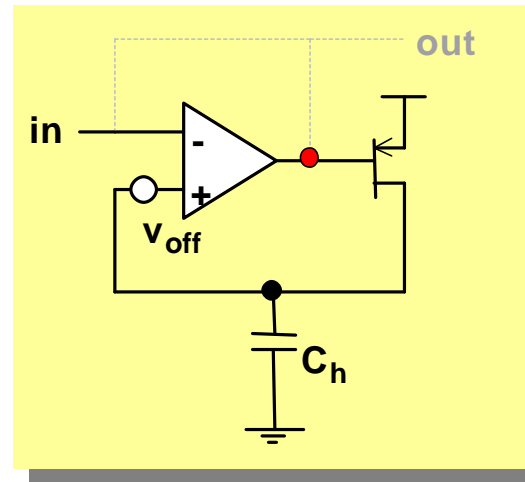


- accuracy impaired by op-amp **offsets** and **CMRR**
 - poor drive capability
 - deadtime until readout
-
- + **self-triggered**
 - + **timing signal**

The two-phase PDH concept

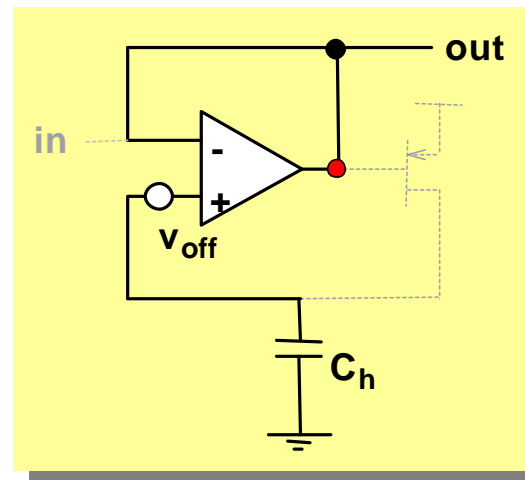
Write phase

- behaves like classical configuration



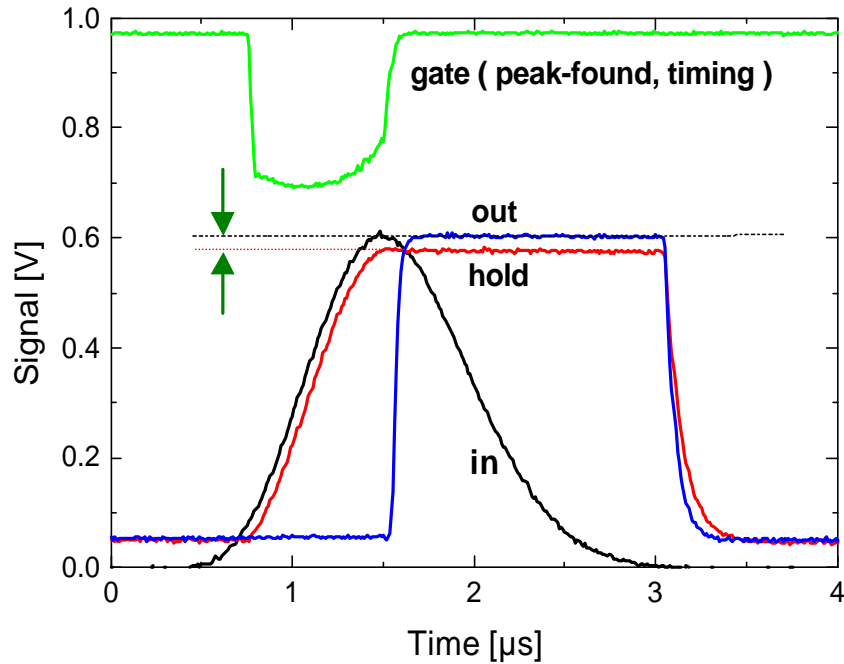
Read phase

- op-amp re-used as buffer
- **offset** and **CMMR errors canceled**
- enables **rail-to-rail** sensing
- good **drive capability**
- **self-switching** (peak found)

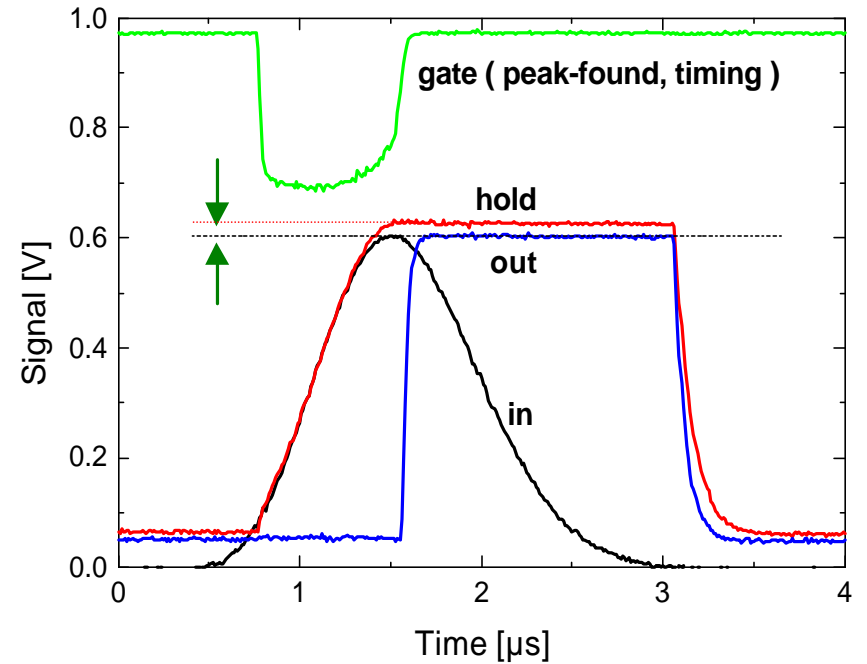


Two-phase PDH : offset cancellation

chip 1 – negative offset



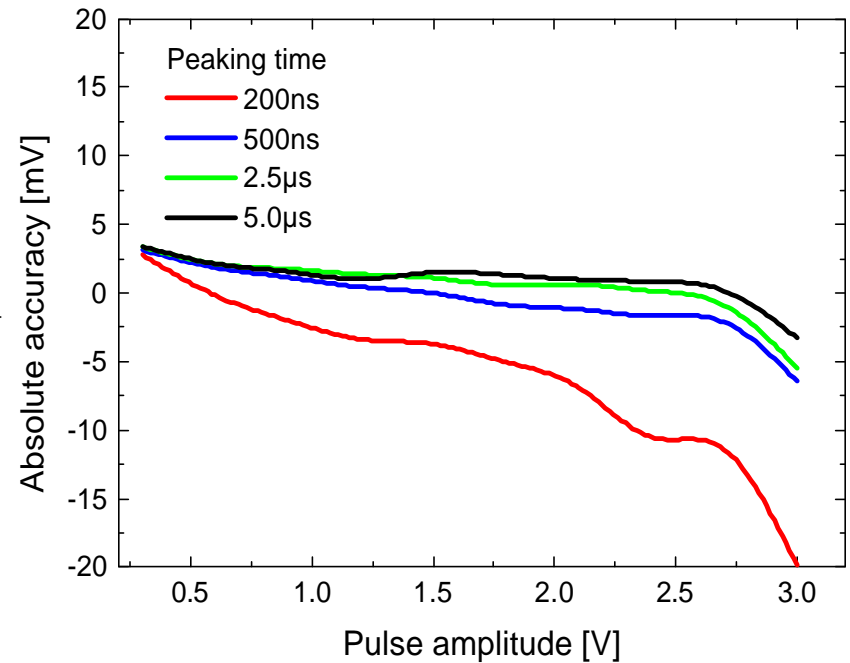
chip 2 – positive offset



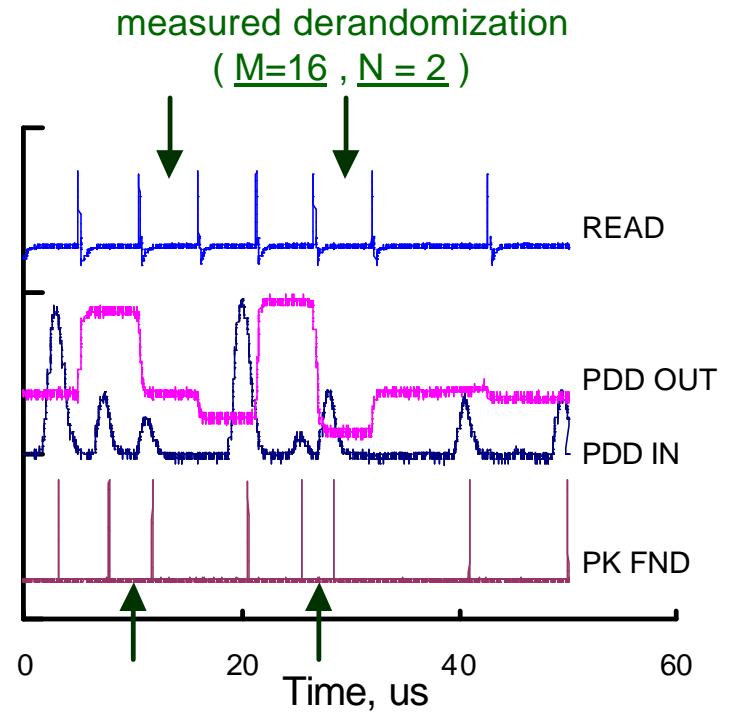
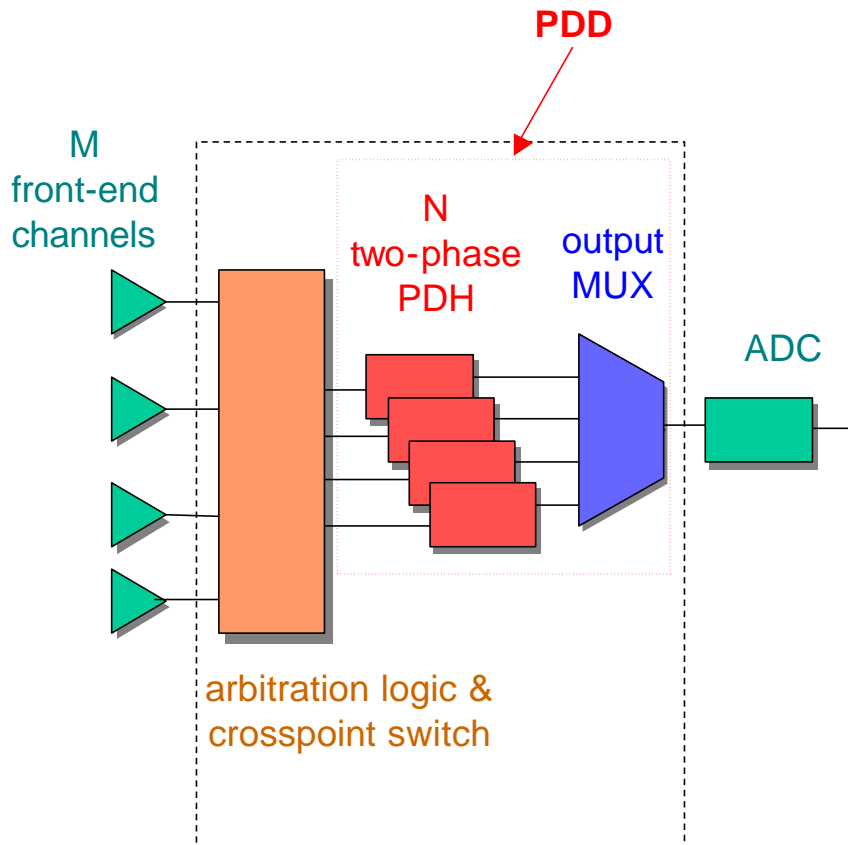
Two-phase PDH : performance

Parameter:	Value: PDDv1 (<i>PDDv2</i>)
Technology	0.35 um CMOS DP4M
Supply voltage	3.3V
Input voltage range	0.3 - 3.0 V
Minimum peaking time	500 (<i>50</i>) ns
Absolute accuracy	< 0.20%
Linearity	< 0.05%
Droop rate	250 mV/s
Timing accuracy	5 ns
Power dissipation	3.5 (2.0) mW/ch

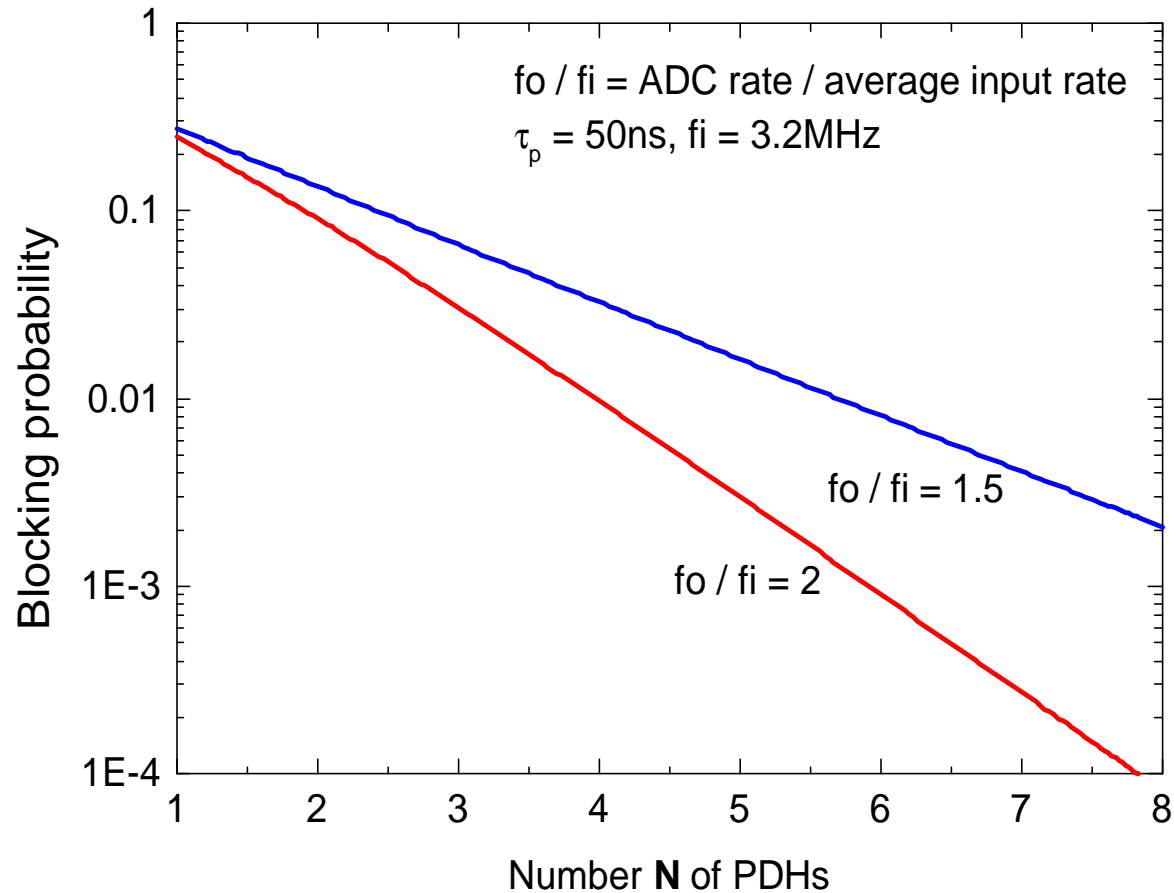
PDDv1 : absolute accuracy



Derandomization with N two-phase PDHs (PDD)



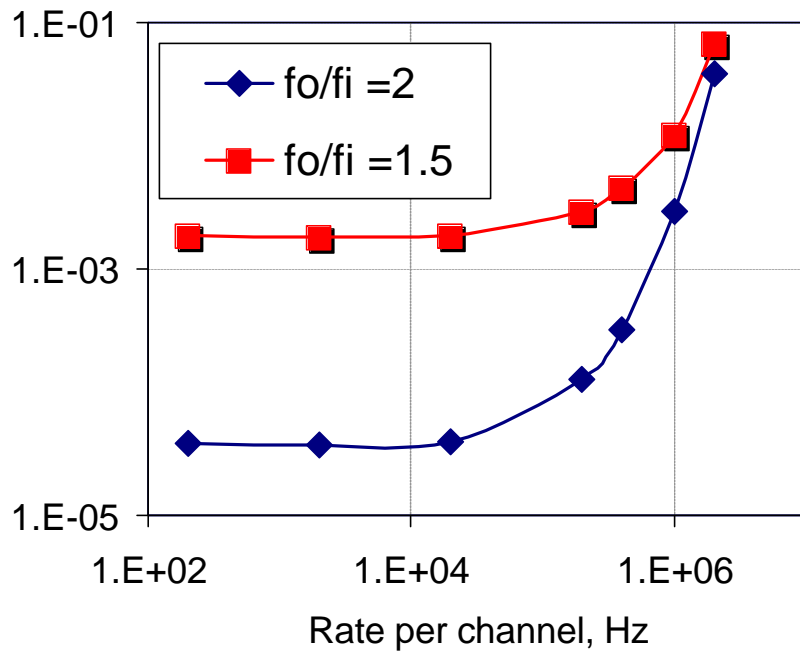
Derandomization efficiency vs N



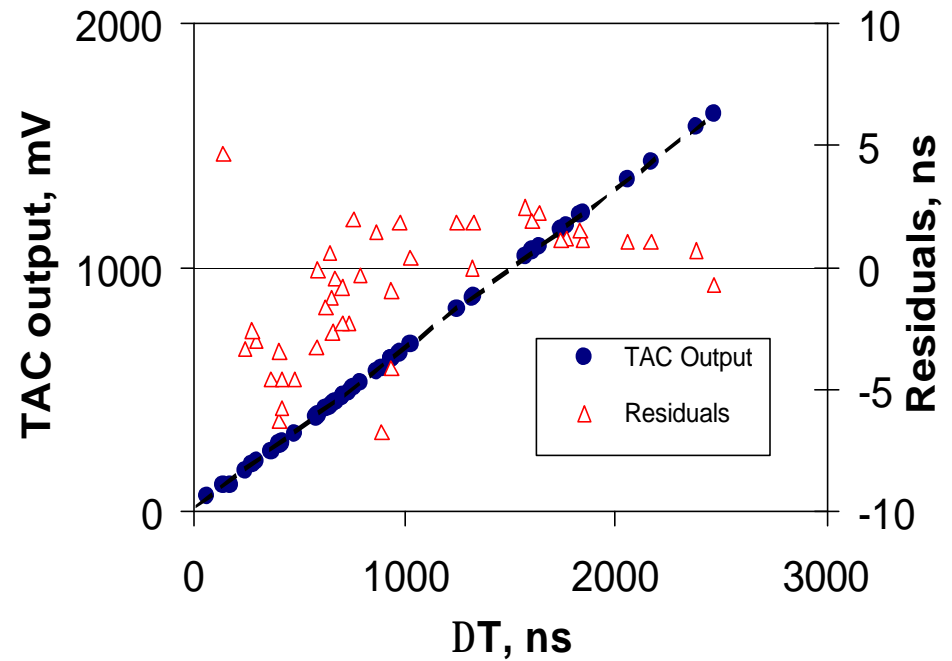
The larger is **N**, the lower can be the **fo/fi** ratio

Derandomization efficiency and TAC linearity

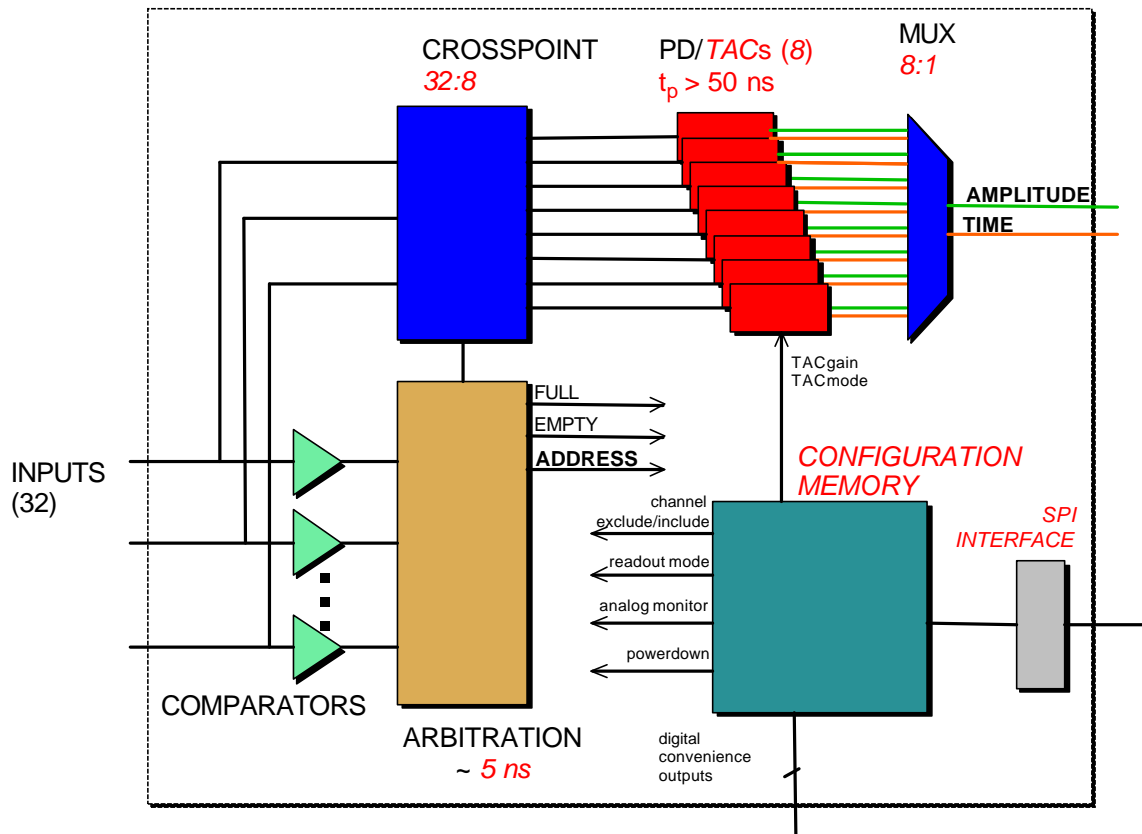
blocking probability



TAC linearity

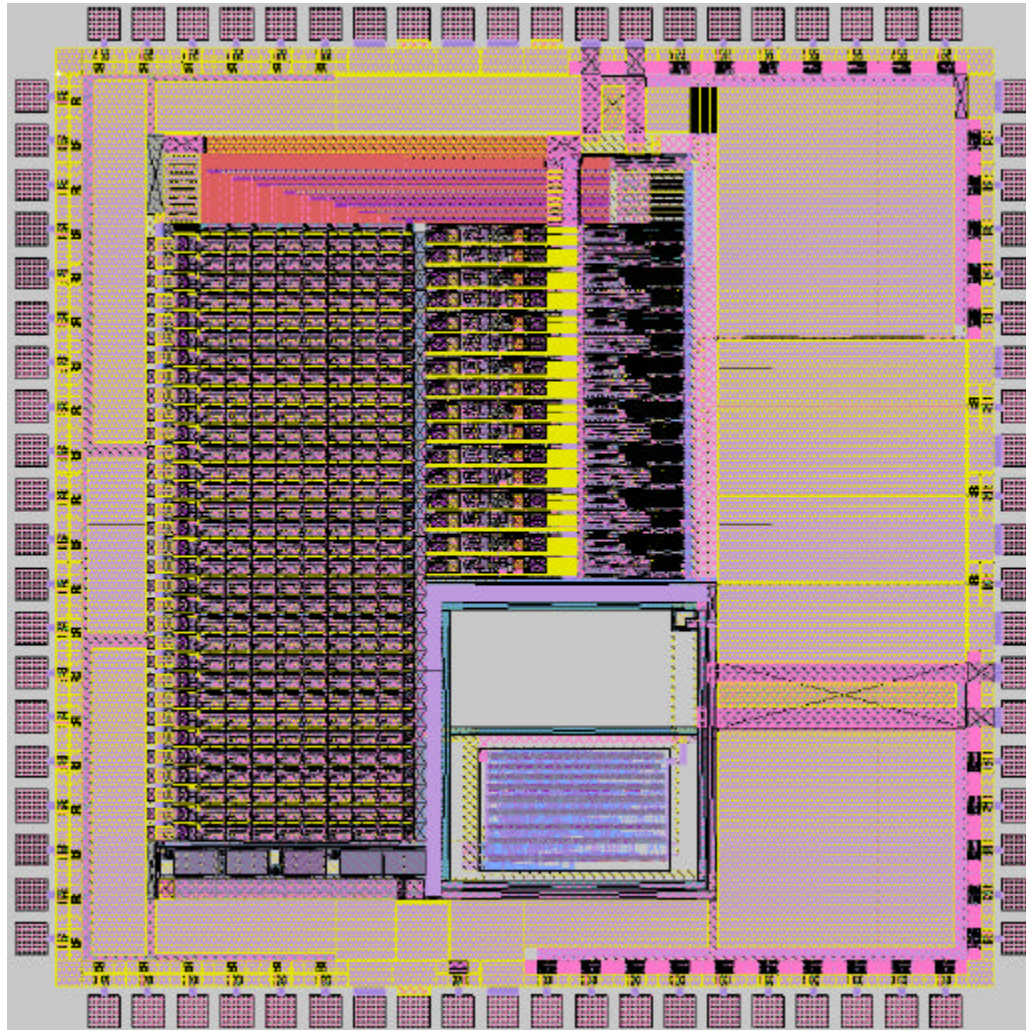


32-channels PDD ASIC



- One-chip solution
- $N_{\text{CHAN}} = 32, N_{\text{PD}} = 8$
- Dual-mode **TAC**
 - risetime
 - time of occurrence
- **Amplitude, address, timing outputs**
- 50 ns minimum pulswidth
- $t_{\text{ARB}} \sim 5$ ns
- Rate capability ~ 10 MHz
- SPI interface:
 - serial configuration of TAC gain and mode
 - arbitration locking
 - channel exclusion
 - powerdown
 - analog monitor
 - Digital convenience outputs (used for configuring companion amplifier chip)
- FIFO-like control and readout interface

32-channels PDD ASIC : layout



size : 3.2 x 3.2 mm²
power : 2mW / channel
technology: 0.35μm CMOS DP4M

Summary

- A generation of high-performance **front-end ASICs** has been developed
 - advanced circuit solutions
 - high reliability, stability, ease of use
 - produced in large quantity
 - implemented in products commercialized by eV
- A generation of **data concentration ASICs** is being developed
 - based on a high-performance peak detector of novel concept
 - self-triggering, multiplexing, derandomizing, sparsifying
 - providing amplitude, timing and address information per event
 - a 32-channels, 8 PDs, 10MHz prototype is in fabrication